THINKING OUTSIDE THE CHIP-MEMS BASED SYSTEMS SOLUTIONS: DESIGNS, TRADEOFFS AND APPLICATIONS

SENSORS EXPO 2009

DONALD E. STEPHENS EXHIBITION CENTER, ROSEMONT ILLINOIS

June 8, 2009 9:00 a.m. to 5:00 p.m.

SESSION ORGANIZER AND CHAIRMAN: ROGER H. GRACE, ROGER GRACE ASSOCIATES

FINAL AGENDA (04-10-09)

9:00-9:05 a.m. Introduction and Welcome- R. Grace, Roger Grace Associates

9:05-9:35 a.m. Smart System Integration through Micro and Nanotechnologies
T. Gessner, Fraunhofer ENS Institute (Germany)..**KEYNOTE**

9:35-9:55 a.m. The 2008 MEMS Commercialization Report Card: Focus on Design for Manufacturing and Test
R. Grace, Roger Grace Associates

9:55-10:15 a.m. Rethinking MEMS Motion Sensing for Portable Devices
C. Fisher, Analog Devices

10:15-10:35 a.m. Successful Applications of Thinking Outside the Chip Strategies
B. Vigna, ST Microelectronics (Italy)

10:35-10:45 a.m. Break

10:45-11:05 a.m. Technological Considerations for Highly Integrated Microsystems
B. Gogoi

11:05-11:25 a.m. Accelerometers at the Olympics
G. O'Brien, MEMSIC; M.A. Maher, SoftMEMS; N. Williams, Tanner Research

11:25-11:45 a.m. Smart Sensors for Industrial Applications
M. Saint- Mard, B. Heusdens, F. Haudry, J. Destine, V. Rochus, J-C Golinval; University of Liege (Belgium)

11:45-12: 05 P.M. MEMS Energy Harvesting for Wireless Sensor Network Applications
R. Andosca, J. Wu , MicroGen Systems; K. Lee, N. Stoffel, Infotonics; P. Tsepeleff, Grape Networks; M. St. Germaine, Leveraging Technology

12: 05-12:50 p.m. Lunch

12:50-1:20 p.m. Integration Issues and Tradeoffs for Microsystems: Strategies and Applications...**KEYNOTE**
K. Najafi, University of Michigan WIMS

1:20-1:40 p.m. Media Isolated Pressure Transducer with Calibration Verfication
A.Flannery, T. Lammers, J. Mallon, axept; A. Brosh, Biotronics

1:40-2:00 p.m. MCU Interface and Processing Considerations for MEMS Motion Sensor Applications
Y. Lee, D. Flowers, J. Murthy, Microchip Technology

2:00-2:20 p.m. Sensor Integration for Expanding Market Opportunities
K. Faust, Kionix

2:20-2:40 p.m. A Generic Environmental Resistant Package for MEMS and Other Semiconductors
S.H. Lee, S. Woo, K. Najafi; ePack Inc.

2:40-3:00 p.m. Packaging and Assembly Issues for MEMS, Microsystems and Sensors **INVITED**
L. Spangler, Aspen Technologies

3:00-3:20 p.m. High Performance Electronic Drive and Sense System for MEMS Gyro
Al Mallah, A. El-Shennawy, A. Shaaban, M. El-Badry, B. Ibrahim, A. Ossama, A.Mokhtar, A. Elsayed, A. Wassal, A. Owies, C. Pisella,Si-Ware Systems (Egypt); C. Kergueris, Tronics Microsystems (France)

3:20-3:30 p.m. Break

3:30-3:50 p.m. Challenges in CMOS to MEMS Interfacing
T. Froehlich, F. Parsaie, Austriamicrosystems

3:50-4:10 p.m. Mixed-Signal CMOS IC-Enabled Relative Humidity and Temperature Sensor
T. Cummins, Chipsensors (Ireland)

4:10-4:30 p.m. Navigating the Minefielld of MEMS and ASICs Integration Options
R. Wender, Triad Semiconductor

4:30-5:00 p.m. Panel Discussion-MEMS Design for Manufacturing, Assembly and Test

B. Bruggeman, SVTC
T. Chang, Asia Pacific Microsystems
D. Cook, Coventor
J. Giachino, UMich WIMS